



# Film Capacitors

## EMI Suppression Capacitors (MKT)

**Series/Type:** B32932 ... B32936

**Date:** June 2020

### Typical applications

- For connection in series with the mains
- For severe ambient conditions
- Capacitive power supply applications
- Energy meters

### Climatic

- Max. operating temperature: 105 °C
- Climatic category (IEC 60068-1:2013): 40/105/56

### Features

- High stability of capacitance value
- X2 safety approval (up to 2.2 µF)
- RoHS-compatible
- AEC-Q200D compliant

### Construction

- Dielectric: metallized polyester
- Internal series connection
- Plastic case (UL 94 V-0)
- Epoxy resin sealing, flame-retardant

### Terminals

- Parallel wire leads, lead-free tinned
- Standard lead lengths: 6 – 1 mm
- Special lead lengths available on request

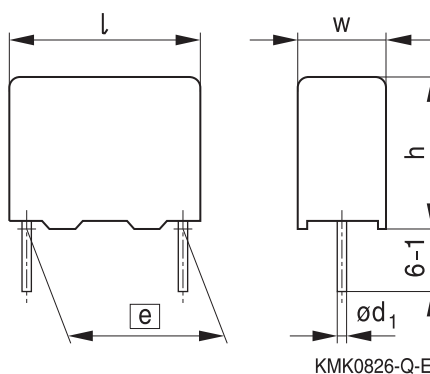
### Marking

Manufacturer's logo, lot number, date code, rated capacitance (coded), capacitance tolerance (code letter), rated AC voltage (IEC), series number, sub-class (X2), dielectric code (MKT), climatic category

### Delivery mode

Bulk (untaped, lead length 6 - 1 mm)  
Taped (Ammo pack or reel)

### Dimensional drawing

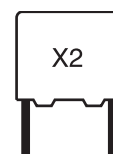


Dimensions in mm

Lead spacing $e \pm 0.4$	Lead diameter $d_1 \pm 0.05$	Type
15	0.8	B32932
22.5	0.8	B32933
27.5	0.8	B32934
37.5	1.0	B32936

B32932 ... B32936

X2 heavy duty series / 305 V AC



### Marking example

M123123123 A XX-1 $\mu$ 5 M 305V~
B3293 X2 MKT/SH 40/105/56/B 

KMK1318-E

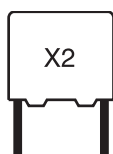
### Approvals

Approval mark	Standards	Certificate
	EN 60384-14:2014/A1:2016 IEC 60384-14:2013/AMD1:2016	40028058
	UL 60384-14:2014	E97863
	CSA E60384-14:2013	E97863

Note: X2 safety approval for  $C \leq 2.2 \mu\text{F}$

### Overview of available types

Lead spacing	15 mm	22.5 mm	27.5 mm	37.5 mm
Type	B32932	B32933	B32934	B32936
$C_R$ ( $\mu\text{F}$ )				
0.047				
0.068				
0.10				
0.15				
0.22				
0.33				
0.47				
0.56				
0.68				
0.82				
1.0				
1.5				
2.2				



**B32932 ... B32936**

**X2 heavy duty series / 305 V AC**

### Ordering codes and packing units

Lead spacing mm	C <sub>R</sub> μF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ	X2 safety appr.
15	0.047	5.0 × 10.5 × 18.0	B32932A3473+***	4680	5200	4000	X
	0.068	5.0 × 10.5 × 18.0	B32932A3683+***	4680	5200	4000	X
	0.10	6.0 × 11.0 × 18.0	B32932A3104+***	3840	4400	4000	X
	0.15	7.0 × 12.5 × 18.0	B32932A3154+***	3320	3600	4000	X
	0.22	8.5 × 14.5 × 18.0	B32932A3224+***	2720	2800	2000	X
	0.33	9.0 × 17.5 × 18.0	B32932A3334+***	2560	2800	2000	X
	0.47	11.0 × 18.5 × 18.0	B32932A3474M***	–	2200	1200	X
22.5	0.10	6.0 × 15.0 × 26.5	B32933A3104+***	2720	2800	2880	X
	0.15	6.0 × 15.0 × 26.5	B32933A3154+***	2720	2800	2880	X
	0.22	7.0 × 16.0 × 26.5	B32933A3224+***	2320	2400	2520	X
	0.33	7.0 × 16.0 × 26.5	B32933A3334+***	2320	2400	2520	X
	0.47	8.5 × 16.5 × 26.5	B32933A3474M***	1920	2000	2040	X
	0.47	10.5 × 16.5 × 26.5	B32933B3474+***	1560	1600	2160	X
	0.56	10.5 × 16.5 × 26.5	B32933A3564+***	1560	1600	2160	X
	0.68	10.5 × 18.5 × 26.5	B32933A3684+***	1560	1600	2160	X
	0.82	12.0 × 22.0 × 26.5	B32933A3824+***	–	–	1800	X
	1.0	12.0 × 22.0 × 26.5	B32933A3105M***	–	–	1800	X
	1.0	14.5 × 29.5 × 26.5	B32933B3105+***	–	–	1040	X
	1.5	14.5 × 29.5 × 26.5	B32933A3155+***	–	–	1040	X

X = approval granted

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

#### Composition of ordering code

+ = Capacitance tolerance code:

M = ±20%

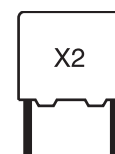
K = ±10%

\*\*\* = Packaging code:

289 = Straight terminals, Ammo pack

189 = Straight terminals, Reel

000 = Straight terminals, Untaped (standard lead length 6 – 1 mm)


**Ordering codes and packing units**

Lead spacing mm	C <sub>R</sub> μF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ	X2 safety appr.
27.5	0.47	11.0 × 19.0 × 31.5	B32934A3474+***	–	1400	1280	X
	0.56	11.0 × 19.0 × 31.5	B32934A3564+***	–	1400	1280	X
	0.68	11.0 × 19.0 × 31.5	B32934A3684+***	–	1400	1280	X
	0.82	11.0 × 19.0 × 31.5	B32934A3824+***	–	1400	1280	X
	1.0	11.0 × 19.0 × 31.5	B32934A3105M***	–	1400	1280	X
	1.0	11.0 × 21.0 × 31.5	B32934B3105+***	–	1400	1280	X
	1.5	13.5 × 23.0 × 31.5	B32934B3155M***	–	1200	1120	X
	1.5	14.0 × 24.5 × 31.5	B32934D3155+***	–	–	1040	X
	2.2	18.0 × 27.5 × 31.5	B32934B3225+***	–	–	800	X
37.5	1.0	12.0 × 22.0 × 41.5	B32936A3105+***	–	–	1620	X
	1.5	12.0 × 22.0 × 41.5	B32936A3155+***	–	–	1620	X
	2.2	14.0 × 25.0 × 41.5	B32936A3225+***	–	–	1380	X

X = approval granted

MOQ = Minimum Order Quantity, consisting of 4 packing units.

Further intermediate capacitance values on request.

**Composition of ordering code**

+ = Capacitance tolerance code:

M = ±20%

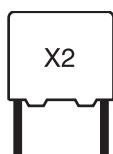
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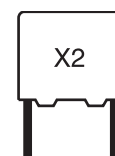
B32932 ... B32936

X2 heavy duty series / 305 V AC

### Technical data

Reference standard: IEC 60384-14:2013/AMD1:2016 and AEC-Q200D.

Max. operating temperature $T_{op,max}$ ( $T_{op} = T_A + \text{self-heating}$ )	+105 °C		
Dissipation factor $\tan \delta$ (in $10^{-3}$ ) at 20 °C (upper limit values)	at	$C \leq 1 \mu\text{F}$	$C > 1 \mu\text{F}$
	1 kHz	8	8
	10 kHz	15	–
Insulation resistance $R_{ins}$ or time constant $\tau = C_R \cdot R_{ins}$ at 20 °C, rel. humidity $\leq 65\%$ (minimum as-delivered values)	$C_R \leq 0.33 \mu\text{F}$		$C_R > 0.33 \mu\text{F}$
	30 000 M $\Omega$		10 000 s
DC test voltage	1312 V DC, 2 s ( $4.3 \cdot V_R$ according to IEC 60384-14)		
Passive flammability category to IEC 40 (CO) 752	B		
Capacitance tolerances (measured at 1 kHz)	$\pm 10\%$ (K), $\pm 20\%$ (M)		
Rated AC voltage ( IEC 60384-14 )	305 V (50/60 Hz)		
Maximum continuous DC voltage $V_{DC}$	500 V at $T_{op} \leq 85 \text{ °C}$ 1.5% / °C derating when $85 \text{ °C} < T_{op} \leq 110 \text{ °C}$		
Operating voltage $V_{op}$ at high temperature	$T_{op} \leq 105 \text{ °C}$		$V_{op} = 1.25 \cdot V_{AC}$ (1000 h)
	Damp heat test		
Limit values after damp heat test	Test conditions:		
	1. Temperature: +85 °C $\pm 2 \text{ °C}$ Relative humidity (RH): 85% $\pm 2\%$ Test duration: 1000 hours Voltage value: 240 V AC, 50 Hz  2. Temperature: +40 °C $\pm 2 \text{ °C}$ Relative humidity (RH): 93% $\pm 2\%$ Test duration: 2000 hours Voltage value: 305 V AC, 50 Hz		
Limit values after damp heat test	Capacitance change ( $\Delta C/C$ ): $\leq 10\%$		
	Dissipation factor change ( $\Delta \tan \delta$ ): $\leq 5 \cdot 10^{-3}$ (at 1 kHz)		
	$\Delta \tan \delta / \tan \delta$ : $\leq 100\%$ (at 10 kHz)		
	Insulation resistance $R_{ins}$ or time constant $\tau = C_R \cdot R_{ins}$ : $> 10 \text{ M}\Omega$		



### Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/μs.

"k<sub>0</sub>" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in V<sup>2</sup>/μs.

*Note:*

*The values of dV/dt and k<sub>0</sub> provided below must not be exceeded in order to avoid damaging the capacitor.*

### dV/dt and k<sub>0</sub> values

Lead spacing (mm)	15	22.5	27.5	37.5
dV/dt (V/μs)	90	50	35	25
k <sub>0</sub> (V <sup>2</sup> /μs)	108000	60000	42000	30000

### Mounting guidelines

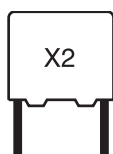
#### 1 Soldering

##### 1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Evaluation criteria:	
Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder



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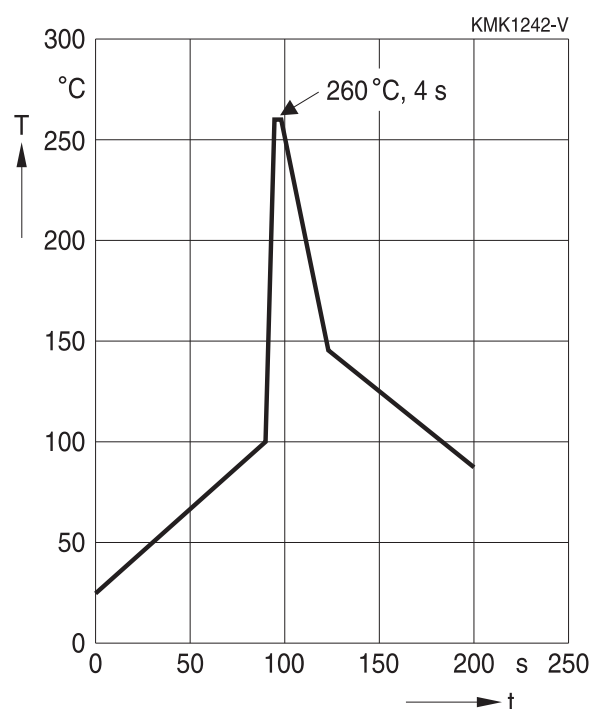
**X2 heavy duty series / 305 V AC**

## 1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1.

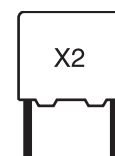
Conditions:

Series	Solder bath temperature	Soldering time
MKT boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP		
MKP (lead spacing >7.5 mm)		
MKT boxed (case 2.5 × 6.5 × 7.2 mm)	260 ±5 °C	5 ±1 s
MKP (lead spacing ≤7.5 mm)		<4 s
MKT uncoated (lead spacing ≤10 mm)		recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)
MKT insulated (B32559)		



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
$\tan \delta$	As specified in sectional specification





### 1.3 General notes on soldering

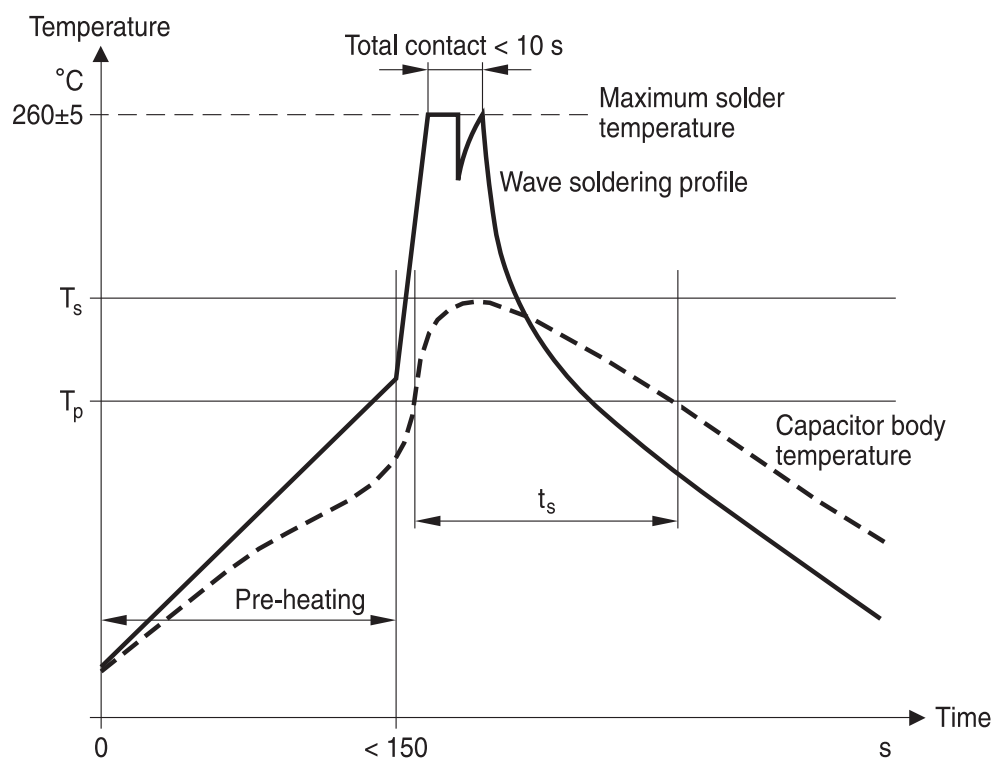
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature  $T_{max}$ . Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:  
diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

### Recommendations

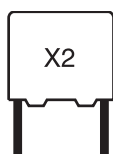
As a reference, the recommended wave soldering profile for our film capacitors is as follows:



$T_s$ : Capacitor body maximum temperature at wave soldering

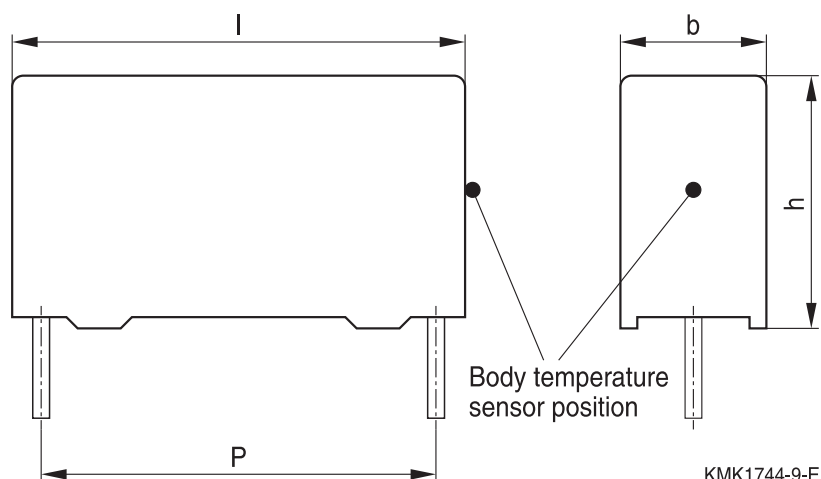
$T_p$ : Capacitor body maximum temperature at pre-heating

KMK1745-A-E



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X2 heavy duty series / 305 V AC



Body temperature should follow the description below:

- MKP capacitor
  - During pre-heating:  $T_p \leq 110 \text{ }^\circ\text{C}$
  - During soldering:  $T_s \leq 120 \text{ }^\circ\text{C}$ ,  $t_s \leq 45 \text{ s}$
- MKT capacitor
  - During pre-heating:  $T_p \leq 125 \text{ }^\circ\text{C}$
  - During soldering:  $T_s \leq 160 \text{ }^\circ\text{C}$ ,  $t_s \leq 45 \text{ s}$

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

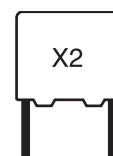
In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor ( $T_s$ ) must be  $\leq 120 \text{ }^\circ\text{C}$ .

One recommended condition for manual soldering is that the tip of the soldering iron should be  $< 360 \text{ }^\circ\text{C}$  and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings  $\leq 10 \text{ mm}$  (B32560/B32561) the following measures are recommended:

- pre-heating to not more than  $110 \text{ }^\circ\text{C}$  in the preheater phase
- rapid cooling after soldering

Please refer to our Film Capacitors Data Book in case more details are needed.



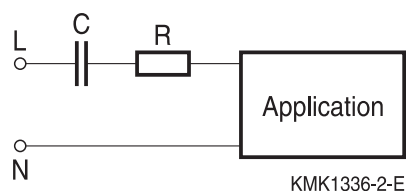
## Application note for the different possible X1 / X2 positions

### In series with the powerline (i.e. capacitive power supply)

Typical Applications:

- Power meters
- ECUs for white goods and household appliances
- Different sensor applications
- Severe ambient conditions

#### Basic circuit



#### Required features

- High capacitance stability over the lifetime
- Narrow tolerances for a controlled current supply

#### Recommended product series

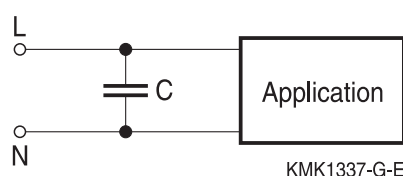
- B3293\* (305 V AC) heavy duty with EN approval for X2 (UL Q1/2010)
- B3265\* MKP series  
standard MKP capacitor without safety approvals
- B3267\*L MKP series  
standard MKP capacitor without safety approvals
- B3292\*H/J (305 V AC), severe ambient condition, approved as X2

### In parallel with the powerline

Typical Applications:

Standard X2 are used parallel over the mains for reducing electromagnetic interferences coming from the grid. For such purposes they must meet the applicable EMC directives and standards.

#### Basic circuit

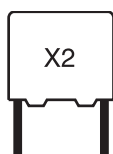


#### Required features

- Standard safety approvals (ENEC, UL, CSA, CQC)
- High pulse load capability
- Withstand surge voltages

#### Recommended product series

- B3292\*C/D (305 V AC)  
standard series, approved as X2
- B3291\* (330 V AC), approved as X1
- B3291\* (530 V AC), approved as X1
- B3291\* (550 V AC), approved as X1
- B3292\*H/J (305 V AC), severe ambient condition, approved as X2



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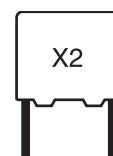
X2 heavy duty series / 305 V AC

## Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of TDK Electronics.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6:2007. TDK Electronics offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"



Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

### Design of our capacitors

Our EMI capacitors use polypropylene (PP) film metalized with a thin layer of Zinc (Zn). The following key points have made this design suitable to IEC/UL testing, holding a minimum size.

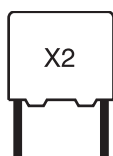
- Overvoltage AC capability with very high temperature Endurance test of IEC 60384-14:2013 (4<sup>th</sup> edition) / UL 60384-14:2014 (2<sup>nd</sup> edition) must be performed at  $1.25 \times V_R$  at maximum temperature, during 1000 hours, with a capacitance drift less than 10%.
- Higher breakdown voltage withstanding if compared to other film metallizations, like Aluminum. IEC 60384-14:2013 (4<sup>th</sup> edition) / UL 60384-14:2014 (2<sup>nd</sup> edition) establishes high voltage tests performed at  $4.3 \times V_R$  – 1 minute, impulse testing at 2500 V for  $C = 1 \mu\text{F}$  and active flammability tests.
- Damp heat steady state: 40 °C/ 93% RH / 56 days. (without voltage or current load)

### Effect of humidity on capacitance stability

Long contact of a film capacitor with humidity can produce irreversible effects. Direct contact with liquid water or excess exposure to high ambient humidity or dew will eventually remove the film metallization and thus destroy the capacitor. Plastic boxed capacitors must be properly tested in the final application at the worst expected conditions of temperature and humidity in order to check if any parameter drift may provoke a circuit malfunction.

In case of penetration of humidity through the film, the layer of Zinc can be degraded, specially under AC operation (change of polarity), accelerated by the temperature, provoking an increment of the serial resistance of the electrode and eventually a reduction of the capacitance value. For DC operation, the parameter drift is much less.

Plastic boxes and resins can not protect 100% against humidity. Metal enclosures, resin potting or coatings or similar measures by customers in their applications will offer additional protection against humidity penetration.



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X2 heavy duty series / 305 V AC

### Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.

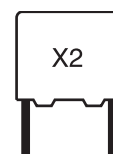
Detailed information can be found on the Internet under [www.tdk-electronics.tdk.com/orderingcodes](http://www.tdk-electronics.tdk.com/orderingcodes).

### Correlation of data sheet values and modelling tool outputs

Data sheet values and results of design tools may deviate as they have not been derived in the same context.

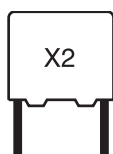
While data sheets show individual parameter statements without considering a possible dependency to other parameters. Tools model a complete given scenario as input and processed inside the tool.

Furthermore as we constantly strive to improve our models, the results of tools can change over time and be a non-binding indication only.



## Symbols and terms

Symbol	English	German
$\alpha$	Heat transfer coefficient	Wärmeübergangszahl
$\alpha_C$	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
$\beta_C$	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
$C_R$	Rated capacitance	Nennkapazität
$\Delta C$	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
$\Delta t$	Time interval	Zeitintervall
$\Delta T$	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
$\Delta V$	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
$f_1$	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
$f_2$	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
$f_r$	Resonant frequency	Resonanzfrequenz
$F_D$	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
$F_T$	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
$I_C$	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)

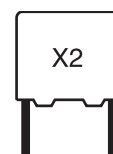


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X2 heavy duty series / 305 V AC

Symbol	English	German
$I_{RMS}$	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
$i_z$	Capacitance drift	Inkonstanz der Kapazität
$k_0$	Pulse characteristic	Impuls Kennwert
$L_S$	Series inductance	Serieninduktivität
$\lambda$	Failure rate	Ausfallrate
$\lambda_0$	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
$\lambda_{test}$	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
$P_{diss}$	Dissipated power	Abgegebene Verlustleistung
$P_{gen}$	Generated power	Erzeugte Verlustleistung
$Q$	Heat energy	Wärmeenergie
$\rho$	Density of water vapor in air	Dichte von Wasserdampf in Luft
$R$	Universal molar constant for gases	Allg. Molarkonstante für Gas
$R$	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
$R_i$	Internal resistance	Innenwiderstand
$R_{ins}$	Insulation resistance	Isolationswiderstand
$R_P$	Parallel resistance	Parallelwiderstand
$R_S$	Series resistance	Serienwiderstand
$S$	severity (humidity test)	Schärfegrad (Feuchtetest)
$t$	Time	Zeit
$T$	Temperature	Temperatur
$\tau$	Time constant	Zeitkonstante
$\tan \delta$	Dissipation factor	Verlustfaktor
$\tan \delta_D$	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
$\tan \delta_P$	Parallel component of dissipation factor	Parallelanteil des Verlustfaktors
$\tan \delta_S$	Series component of dissipation factor	Serienanteil des Verlustfaktors
$T_A$	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
$T_{max}$	Upper category temperature	Obere Kategorietemperatur
$T_{min}$	Lower category temperature	Untere Kategorietemperatur
$t_{OL}$	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
$T_{op}$	Operating temperature, $T_A + \Delta T$	Betriebstemperatur, $T_A + \Delta T$
$T_R$	Rated temperature	Nenntemperatur
$T_{ref}$	Reference temperature	Referenztemperatur
$t_{SL}$	Reference service life	Referenz-Lebensdauer





Symbol	English	German
$V_{AC}$	AC voltage	Wechselspannung
$V_C$	Category voltage	Kategorie <span>spannung</span>
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
$V_{CD}$	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
$V_{ch}$	Charging voltage	Ladespannung
$V_{DC}$	DC voltage	Gleichspannung
$V_{FB}$	Fly-back capacitor voltage	Spannung (Flyback)
$V_i$	Input voltage	Eingangsspannung
$V_o$	Output voltage	Ausgangsspannung
$V_{op}$	Operating voltage	Betriebsspannung
$V_p$	Peak pulse voltage	Impuls-Spitzen <span>spannung</span>
$V_{pp}$	Peak-to-peak voltage Impedance	Spannungshub
$V_R$	Rated voltage	Nennspannung
$\hat{V}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
$V_{RMS}$	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
$V_{SC}$	S-correction voltage	Spannung bei Anwendung "S-correction"
$V_{sn}$	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
$Z$	Impedance	Scheinwiderstand
$e$	Lead spacing	Rastermaß

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## Important notes

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